3.3 V ECL +4 Divider

Description

The MC100LVEL33 is an integrated ÷4 divider. The LVEL is functionally equivalent to the EL33 and works from a 3.3 V supply.

The reset pin is asynchronous and is asserted on the rising edge. Upon power-up, the internal flip-flops will attain a random state; the reset allows for the synchronization of multiple LVEL33's in a system.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

- 630 ps Typical Propagation Delay
- 4.0 GHz Typical Maximum Frequency
- ESD Protection:
 - ♦ > 4 KV Human Body Model
 - → > 200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: V_{CC} = 3.0 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC}= 0 V with V_{EE} = -3.0 V to -3.8 V
- Internal Input Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity:
 - Level 1 for SOIC-8
 - ◆ Level 3 for TSSOP-8
 - For Additional Information, see Application Note <u>AND8003/D</u>
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 130 Devices
- · These Devices are Pb-Free, Halogen Free and are RoHS Compliant



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SOIC-8 NB D SUFFIX CASE 751-07 TSSOP-8 DT SUFFIX CASE 948R-02

MARKING DIAGRAMS*





SOIC-8

TSSOP-8

A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note <u>AND8002/D</u>.

ORDERING INFORMATION

Device	Package	Shipping†
MC100LVEL33DG	SOIC-8 NB (Pb-Free)	98 Units / Tube
MC100LVEL33DR2G	SOIC-8 NB (Pb-Free)	2500Tape & Reel
MC100LVEL33DTG	TSSOP-8 (Pb-Free)	100 Units / Tube
MC100LVEL33DTR2G	TSSOP-8 (Pb-Free)	2500 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

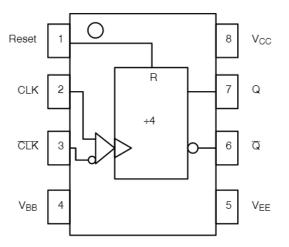


Figure 1. Logic Diagram and Pinout Assignment

Table 1. PIN DESCRIPTION

ıts

^{*} Pins will default LOW when open due to internal 75 k $\!\Omega$ resistor to $V_{\mbox{\footnotesize{EE}}}$

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8 to 0	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-8 to 0	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$ V_I \leq V_{CC} \\ V_I \geq V_{EE} $	6 to 0 -6 to 0	V
l _{out}	Output Current	Continuous Surge		50 100	mA
I _{BB}	V _{BB} Sink/Source			± 0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θЈА	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 NB SOIC-8 NB	190 130	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8 NB	41 to 44 ±5%	°C/W
θЈА	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ±5%	°C/W
T _{sol}	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

^{**} Pins will default to 1/2 V_{CC} when open due to internal resistors: 75 k Ω to V_{EE} and 75 k Ω to V_{CC}

Table 3. LVPECL DC CHARACTERISTICS (V_{CC} = 3.3 V; V_{EE} = 0.0 V (Note 1))

			-40°C 25°C								
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		33	37		33	37		35	39	mA
V _{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V _{OL}	Output LOW Voltage (Note 2)-	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V _{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 3) V _{PP} < 500 Mv V _{PP} ≥ 500 mV	1.2 1.4		2.9 2.9	1.1 1.3		2.9 2.9	1.1 1.3		2.9 2.9	V
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current Other CLK	0.5 -600			0.5 -600			0.5 -600			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
 Outputs are terminated through a 50 Ω resistor to V_{CC} 2.0 V.
 V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1 V.

Table 4. LVNECL DC CHARACTERISTICS (V_{CC} = 0.0 V; V_{EE} = -3.3 V (Note 1))

		-40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		33	37		33	37		35	39	mA
V _{OH}	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V _{OL}	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
V _{BB}	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 3) V _{PP} < 500 Mv V _{PP} ≥ 500 mV	-2.1 -1.9		-0.4 -0.4	-2.2 -2.0		-0.4 -0.4	-2.2 -2.0		-0.4 -0.4	V
Iн	Input HIGH Current			150			150			150	μА
I _{IL}	Input LOW Current Other CLK	0.5 -600			0.5 -600			0.5 -600			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
 Outputs are terminated through a 50 Ω resistor to V_{CC} 2.0 V.
 V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between Vppmin and 1 V.

Table 5. AC CHARACTERISTICS (V_{CC} = 3.3 V; V_{EE} = 0.0 V or V_{CC} = 0.0 V; V_{EE} = -3.3 V (Note 1))

			-40°C 25°C			85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency	3.4			3.8	4.0		3.8			GHz
tpLH tpHL	Propagation Delay CLK to Q (Diff) CLK to Q (SE) Reset to Q	530 530 500	630 655	730 780 700	570 570 520	670 695	770 820 720	650 650 580	750 775	850 900 780	ps
t _{RR}	Reset Recovery	300			300			300			ps
t _{skew}	Duty Cycle Skew (Note 2)			20			20			20	ps
t _{JITTER}	Cycle-to-Cycle Jitter		0.5	< 1.0		0.5	< 1.0		0.5	< 1.0	ps
V _{PP}	Input Voltage Swing (Differential Configuration)	150		1000	150		1000	150		1000	mV
t _r t _f	Output Rise / Fall Times Q (20%-80%)	120		320	120		320	120		320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. V_{EE} can vary ± 0.3 V.
 2. Duty cycle skew is the difference between T_{PLH} and T_{PHL} .

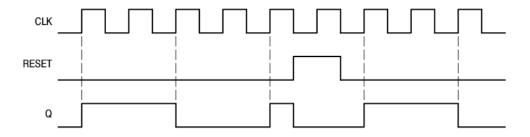


Figure 1. Timing Diagram

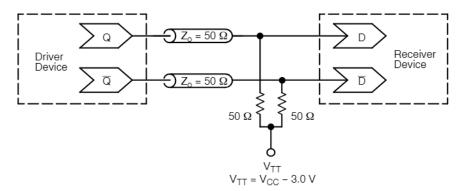


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note <u>AND8020/D</u> – Termination of ECL Logic Devices)

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AND8001/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

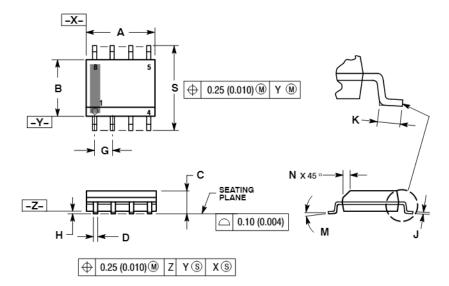
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB **D SUFFIX** CASE 751-07 ISSUE AK



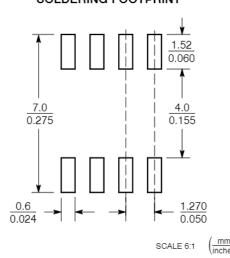
NOTES:

- JTES:
 DIMENSIONING AND TOLERANCING PER
 ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE
 MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006)
- PER SIDE.

 DIMENSION D DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION. 751–01 THRU 751–06 ARE OBSOLETE. NEW STANDARD IS 751–07.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
Н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
K	0.40	1.27	0.016	0.050	
M	0 °	8 °	0 °	8 °	
N	0.25	0.50	0.010	0.020	
s	5.80	6.20	0.228	0.244	

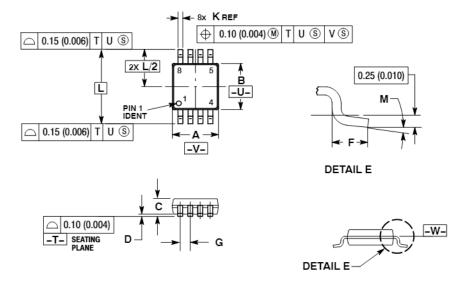
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 DT SUFFIX CASE 948R-02 ISSUE A



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M. 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD
 FLASH. PROTRUSIONS OR GATE BURRS. MOLD
 FLASH OR GATE BURRS SHALL NOT EXCEED
 0.15 (0.006) PER SIDE.
- DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- DIMENSION A AND B ARE TO BE
 DETERMINED AT DATUM PLANE -W-.

	MILLIN	METERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65	BSC	0.026	BSC
K	0.25	0.40	0.010	0.016
L		BSC	0.193	BSC
M	0°	6 °	0°	6°

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